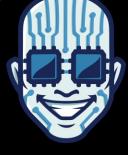
## DESIGNCON 2023 WHERE THE CHIP MEETS THE BOARD

JANUARY 31/-/FEBRUARY 2, 2023

Santa Clara Convention Center Santa Clara, CA



## 2022 Attendee List At-A-Glance

Job Title	Company
Sr. Design Engineer	зм
Electrical Engineer	Abbott Laboratories
Systems Architect	Advanced Technology Services
Sr. Director IoT Security	Aeris
Hardware Development Engineer	Amazon
Lead Electrical Engineer	Amazon
Lead Signal and Power Integrity Engineer	Amazon
Network Engineer	Amazon
Sr. Hardware Lead	Amazon
RF/IO Specialist	AMD
Signal Integrity Engineer	AMD
SI/PI Engineer	AMD
Sr. Packaging Engineer	AMD
Principal Design Engineer	Ampere Computing
Application Engineer	Amphenol
Director, Applications Engineering	Analog Devices
Principal Engineer	Analog Devices
Mechanical Design Engineer	Anritsu
Sr. Design Engineer	Anritsu
Sr. Application Engineer	Ansys
Design Program Manager	Apple
Hardware Design Engineer	Apple
SI/PI Engineer	Apple
EMC Engineer	Apple
System Design Engineer	Apple
Hardware Engineer	Arista Networks
Optical Software Engineer	Arista Networks
Sr. PCB Designer	Arista Networks
Thermal Engineer	Arista Networks
Embedded Software Engineer	ASELSAN
CEO	Astera Labs
Sr. Signal Integrity Engineer	Astera Labs
Design Engineer	Auradine
V.P., Manufacturing	Averatek Corporation
System Engineer	bitByte Lab
Project Engineer	BizLink Technology
Vehicle Cybersecurity Specialist	BMW of North America LLC
PC Board Engineer	Broadcom
IC Design Engineer	Broadcom
VP Research & Development	Cadence
Lead Application Engineer	Cadence

Job Title	Company
Principal Design Engineer	Cadence
Director of Applications Engineering	Caltron Components
MTS - Signal Integrity	Cerebras Systems
ASIC Engineering Technical Leader	Cisco
Electrical Product Engineer	Cisco
Mechanical Engineer	Cisco
Product Engineer	Cisco
Field Applications Engineer	Credo
Sr. Hardware Engineer	Cruise
Application Engineer	DuPont
Principal Engineer	DuPont
Product/Test Engineer	Esperanto Technologies
Electrical Engineer	Foxconn Inc.
Machine Intelligence Hardware Engineer	Google
Semiconductor Risk Lead	Google
Hardware Engineer	Google
Sr. Hardware Engineer	Google
Thermal Engineer	Google
Optical Engineer	Hisense Broadband Inc
Sr. Advanced Electrical Engineer	Honeywell
Sr. Director, System Applications Engineering	Infineon Technologies Americas Corp.
Design Engineer	Intel
Director, Signal & Power Integrity	Intel
Electrical Validation Engineer	Intel
RF Hardware Engineer	Intel
Sr. Electrical Engineer	Intel
Sr. Manager, Product Development Planning	Japan Aviation Electronics Industry
EMC Design Engineer	Juniper Networks
Hardware Design Engineer	Juniper Networks
Signal Integrity Engineer	Juniper Networks
R&D Engineer	Keysight Technologies
Sr. System Architect	Keysight Technologies
Electrical Design Engineer	KLA
Application Engineer	Marvell
Firmware Engineer	Marvell
Hardware Engineer	Marvell
Sr. PCB Designer	Marvell
Principal Engineer	Marvell
Sr. Staff Application Engineer	Marvell
Sr. Engineer	Mayo Clinic



## of attendees recommend, specify, or make the final buying decision

Job Title	Company
Hardware Systems Engineer	Meta
Hardware Engineer	Meta
RF Desense Lead	Meta
RF Engineer	Meta
Signal Integrity Engineer	Meta
Principal System Engineer/HW Platforms	Microchip Technology, Inc.
DRAM Application Engineer	Micron
Field Application Engineer	Micron
Principal Hardware Engineer	Microsoft
Sr. Hardware Engineer	Microsoft
Sr. RF Engineer	Microsoft
Head of Product, Silicon Industry	Microsoft
Sr. SI/PI Engineer	Microsoft
Sr. Manager Product Line	Molex
Electrical Engineering Manager	Molex
Hardware Engineer	NVIDIA
Lead PCB Design Engineer	NVIDIA
Mechanical Engineer	NVIDIA
Sr. Director Switches Hardware	NVIDIA
Lead Design Engineer	NVIDIA
System Architect	NXP Semiconductor
Electrical Engineer	Omron Robotics and Safety Technologies
Principal Component Engineer	Oracle
Application Engineer	Pactech
Computer Engineer	Pactech
Sr. Principal Signal Integrity Engineer	Palo Alto Networks
Director	Panasonic
Sr. Design Engineer	PCB Consulting
Software Engineer	Qualcomm
Sr. Field Application Engineer	Qualcomm
System Design Engineer	Qualcomm
Technical IP Analyst	Rambus Inc
RF Engineer	RF Engineering
PCB Design Specialist	Riedel Communications Company
Hardware Engineer	Roku
Sr. Staff Engineer	Samsung
Application Engineer	Samtec
Electronics Engineer	Sandia National Laboratories
Sr. Hardware Technical Leader	Sanmina
SI/PI Simulation Specialist	SECO SpA
Sr. Characterization Engineer	Semtech

Job Title	Company
Staff Electrical Engineer	Shockwave Medical
Development Test Engineer	Siemens
SI/PI Applications Engineer	Siemens
Sr. Software Engineer	SK Hynix
Signal Integrity Engineer	SK Hynix
Sr. Product Line Manager	Skyworks Inc
Hardware Design Engineer	Solidigm Technology
Applications Engineer	STMicroelectronics
Hardware Design Manager	Supermicro
Hardware Design Engineer	Supermicro
Sr. Staff System Application	Synaptics
Distinguished Architect	Synopsys
R&D Manager	Synopsys
Director, Hardware System Design	Tachyum
System Architect	TE Connectivity
Principal Engineer	TE Connectivity
Signal Integrity Engineer	TE Connectivity
Principal Engineer	Tektronix
Sr. Software Engineer	Tektronix
IoT Services Specialist	Telit
Director of Silicon Technology Engineering	Teradyne
Hardware Engineer	Teradyne
Systems Engineer	Teradyne
Product Engineer	Tesla
Signal and Power Integrity Engineer	Tesla
Analog Design Engineer	Texas Instruments
Applications Engineer	Texas Instruments
Design Engineer	Texas Instruments
Systems Engineer	Texas Instruments
Sr. Engineer - Cabin & Network Systems, Cameras	The Boeing Company
Software Engineer	TikTok
Senior Project Manager	Toyota Motor North America
Director of Automation	Translarity
Field Application Engineer	TTM Technologies, Inc.
System Analyst	United Airlines
Electrical Engineer	Varian Medical Systems
Principal Engineer	Western Digital
Hardware Development Engineer	Western Digital
Head of Hardware	Yohana
Senior Hardware Design Engineer	Zurich Instruments AG

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